
**ETCS Reverse Engineering
Case Study 3:
Hood Otr. Draw Die**



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Reverse Engineering Scanning Process

- Scanning of Assembly & individual parts
- Digital assembly of scan data in assembled position.
- Surface modeling from individual scans in Body (assembled) position.
- Translation of final model customer CAD system: CATIA V4/V5, UG, ProE Etc.

Draw Die



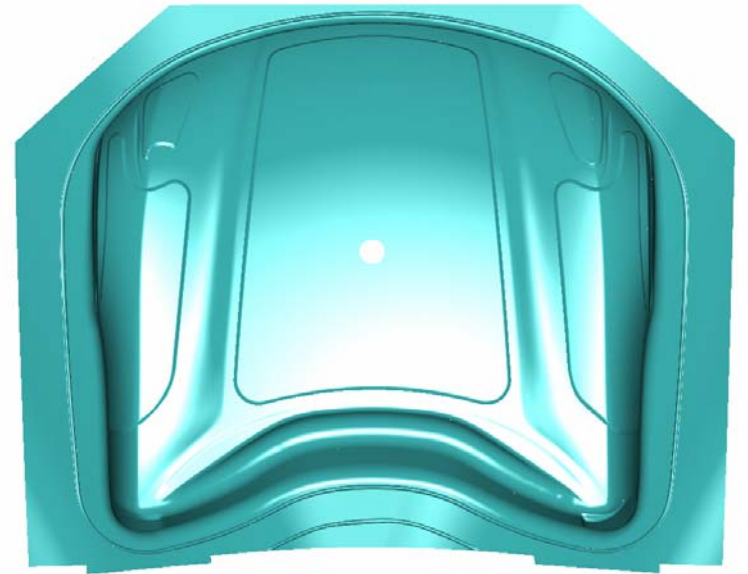
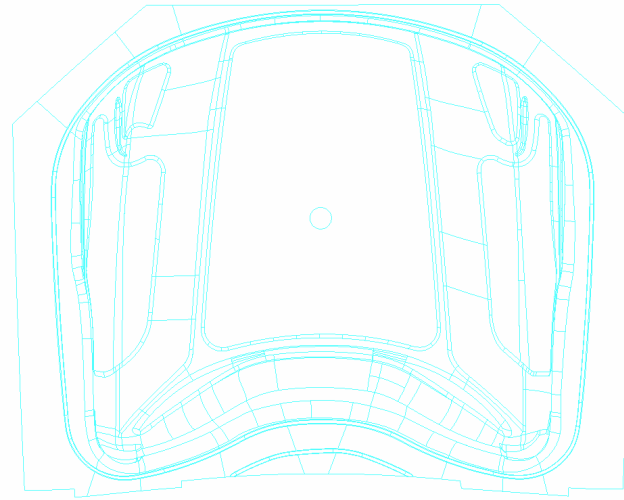
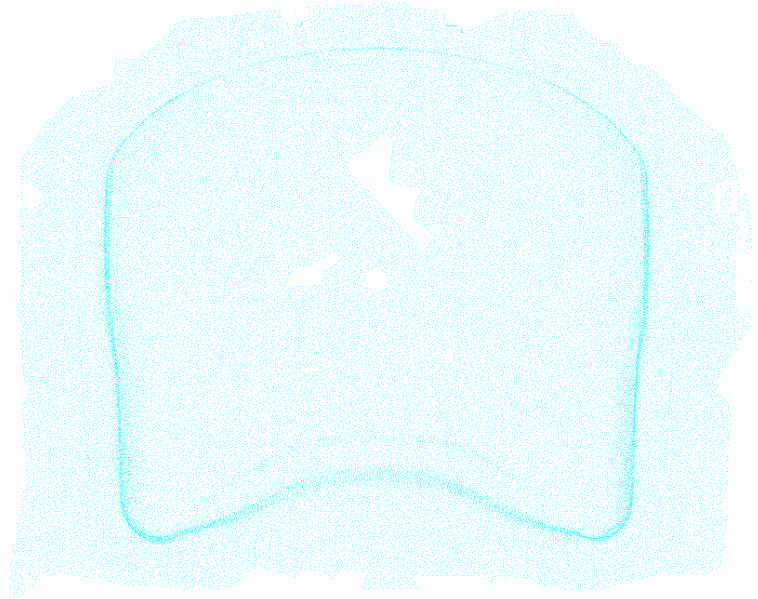
Lower Die



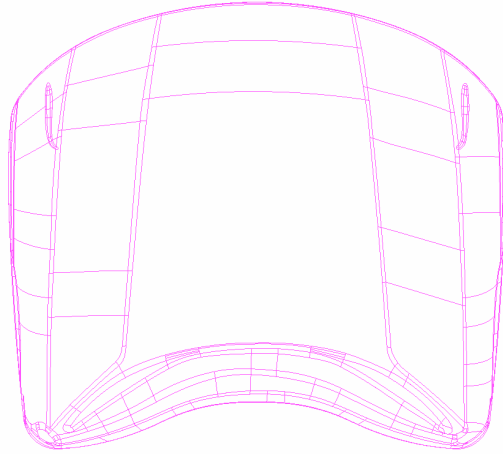
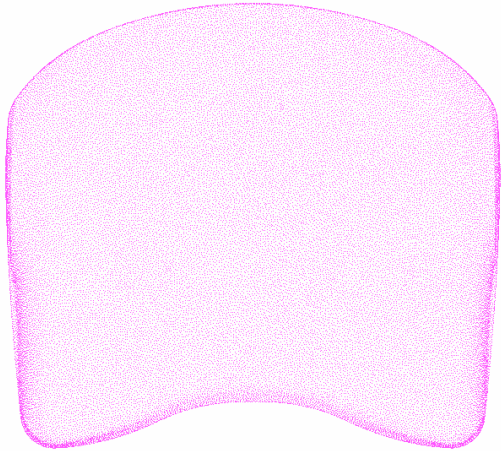
Upper punch and binder ring

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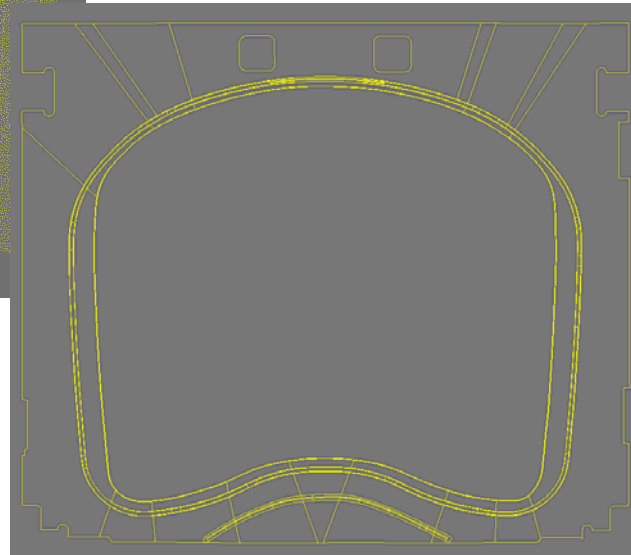
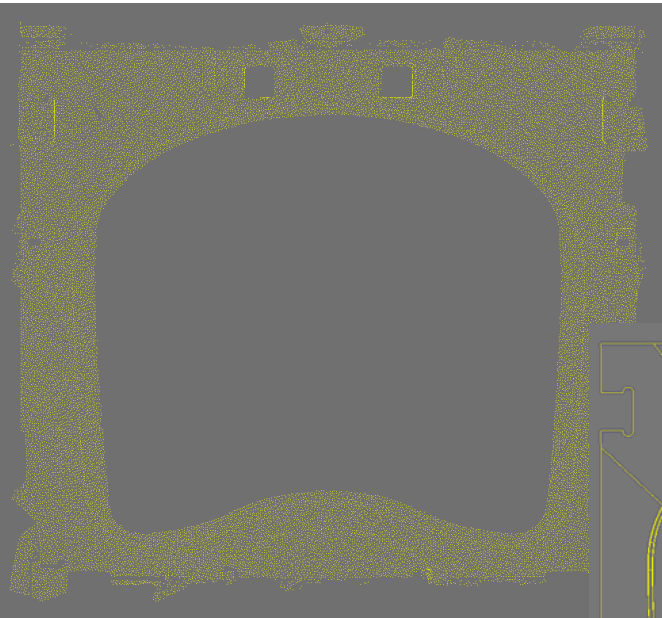
Lower Die



Upper Die/Punch



Upper Binder Ring



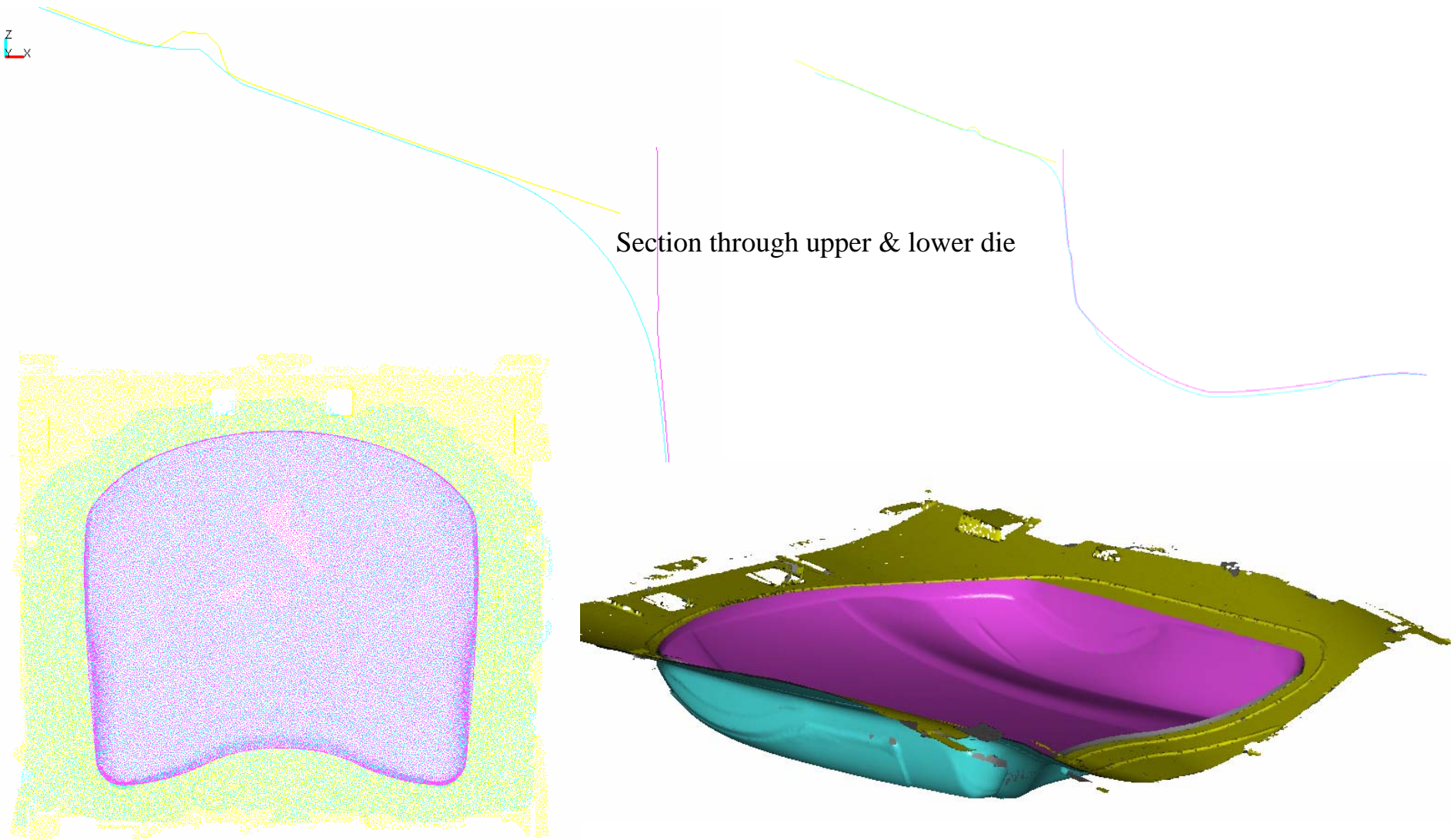
Vent Holes



Small Vent Holes of diameter
3.0mm were accurately measured
using feature mode



Assembled Data in die position at metal thickness



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Final UG file

